

# Product/process change notification

PCN N° 2021-120-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

## Change of mold compound for CoolMOS™ products in package PG-TDSON-8 from Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2021-09-23**
- Infineon aligns with the widely recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.  
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.  
For further details, please visit our website:  
<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG  
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0  
Chairman of the Supervisory Board: Dr. Wolfgang Eder  
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider  
Registered Office: Neubiberg  
Commercial Register: München HRB 126492

# Product/process change notification

**PCN N° 2021-120-A**

▶ **Products affected**

Please refer to attached affected product list  
“pcn\_2021-120-A\_[customer-no].pdf”

▶ **Detailed change information**

**Subject** Change of mold compound for CoolMOS™ products in package PG-TDSON-8 from Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia.

**Reason** Mold compound standardization

<b>Description</b>	<u>Old</u>	<u>New</u>
<b>Mold compound</b>	■ CEL 9240 HF40M3	■ KMC 2110 G-7

▶ **Product identification**

Traceability is ensured via bau number, lot number and date code.

▶ **Impact of change**

Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability.

▶ **Attachments**

pcn_2021-120-A_[customer-no].pdf	affected product list
2_cip21120_a	qualification report

▶ **Time schedule**

- |                              |  |
|------------------------------|--|
| ■ Final qualification report | available  |
| ■ First samples available    | on request                                       |
| ■ Intended start of delivery | 2021-11-15 or earlier based on customer approval |

If you have any questions, please do not hesitate to contact your local sales office.

## PCN2021-120-A

Change of mold compound for CoolMOSTM products in package PG-TDSON-8 from  
Infineon Technologies (Malaysia) Sdn. Bhd., Melaka, Malaysia



Affected products sold to DIGI-KEY (4002348)

Sales name	SP number	OPN	Package	Customer part number
IPLK60R1K0PFD7	SP005354001	IPLK60R1K0PFD7ATMA1	PG-TDSON-8	IPLK60R1K0PFD7ATMA1
IPLK60R1K5PFD7	SP004748878	IPLK60R1K5PFD7ATMA1	PG-TDSON-8	IPLK60R1K5PFD7ATMA1
IPLK60R360PFD7	SP004854666	IPLK60R360PFD7ATMA1	PG-TDSON-8	IPLK60R360PFD7ATMA1
IPLK60R600PFD7	SP004748882	IPLK60R600PFD7ATMA1	PG-TDSON-8	IPLK60R600PFD7ATMA1